


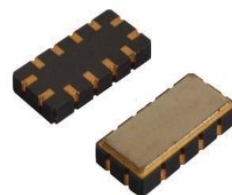
<b>SPECIFICATION SHEET NO.</b>	S0315 - SXF0070RKNSS16	
<b>ORIGINAL MFG/PART NO.</b>	Shengxin SAW/SXF0070RKNSS10	
<b>NEXTGEN PART CODE</b>	SXF0070RKNSS16	Indicate This Code For <a href="#">RFQ</a> /Order
<b>DATE</b>	Mar. 15, 2025	
<b>REVISION</b>	A2	Updated With Most Recent Data
<b>DESCRIPTION AND MAIN PARBMETRICS</b>	<p>SMD SAW Filter, 12 Pads, 1365 Type, SXF Series, Case Code QCC12</p> <p>Case Dimension L13.3*W6.50*H2.0mm</p> <p>Center Frequency 70.00MHz; Insertion Loss: 12dB Typical, 14dB Max.</p> <p>Bandwith 0.8MHz</p> <p>Operating Temp. Range -20°C ~ +70°C</p> <p>Reflow Profile Condition 260°C Max.</p> <p>Package in Tape/Reel, 1000pcs/Reel</p> <p>REACH/RoHS/RoHS III Compliant</p>	
<b>CUSTOMER</b>		
<b>CUSTOMER PART NUMBER</b>		
<b>CROSS REF. PART NUMBER</b>		
<b>MEMO</b>		

<b>VENDOR APPROVE</b>		
Issued/Checked/Approved	  	
Effective Date: Mar. 15, 2025		

<b>CUSTOMER APPROVE</b>
Date:

## MAIN FEATURE

- SMD SAW Filter 1365 Type 12 Pads
- Dimension L13.3\*W6.50\*H2.0mm
- Low-loss SAW Component
- Low Amplitude Ripple
- Sharp Rejections At Both Out-bands
- Bandwith 0.8MHz
- Package Code QCC12
- Ceramic Package For Surface Mounted Technology (SMT)
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level (MSL) 1
- Short Lead Time
- Cross Competitors Parts And More
- REACH/RoHS/RoHS III Compliant



*Image shown is a representation only. Exact specifications should be obtained from the product dimension.*



## APPLICATION

- Bluetooth, Wireless Communication Set
- Communication Electronics
- GPS, Remote Control Application

## ELECTRICAL CHARBCTERISTICS

- See Page 5
- All Products Parameters are Subject To NextGen Components' Final Confirmation.

## HOW TO ORDER

- Please Follow Up Part Code Guide And Indicate NextGen Part Code SXF0070RKNSS16 For RFQ and Order.

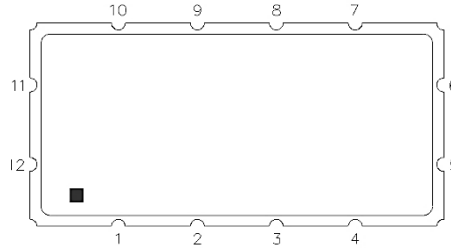
## PART CODE GUIDE

**RFQ**  
[Request For Quotation](#)

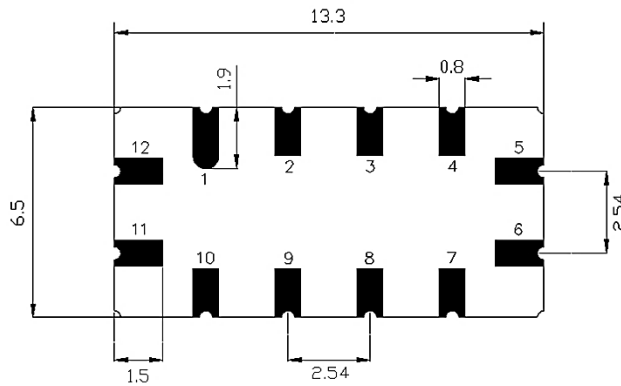
CODE	NAME	KEY SPECIFICATION OPTION
SXF	Series Code	SMD SAW Filter
0070R	Frequency Range Code	0070R: 70.0MHz or Custom Frequency Range
KNS	Internal Control Code	Letter A~Z, a~z or Digits (1-9)
S16	Dimension Code	S16: Case Dimension L13.3*W6.50*H2.0mm, 12 Pads, 1365 Type Case Code QCC12
XX	Special/Custom Parameters Code	Blank: N/A XX: Letter A~Z, a~z or Digits (0~9) for Special/Custom Parameters

**DIMENSION** - Unit: mm, L13.3\*W6.50\*H1.80mm

Top View

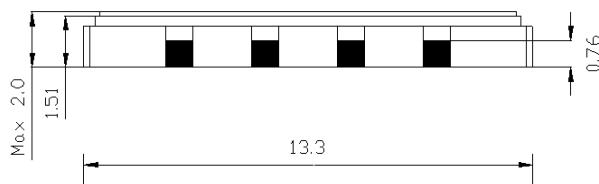


Bottom View



PIN CONFIGURATION	
11	Input
12	Input Ground
5	Output
6	Output Ground
1,2,3,4,7,8,9,10	Ground

Side View



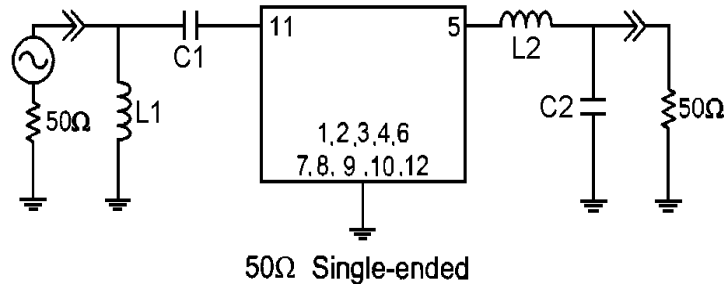
**MAX. RATING & CHARACTERISTICS** - At 25±2°C Ambient Temperature Unless Otherwise Specified.

PARAMETER	SYMBOLS	VALUE	UNITS
RF Power Level	P	10	dBm
DC Voltage	V <sub>DC</sub>	±30	V
Operating Temperature Range	T <sub>A</sub>	-20 to +70	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +85	°C

**ELECTRONICAL CHARACTERISTICS** - At 25±2°C Ambient Temperature Unless Otherwise Specified.

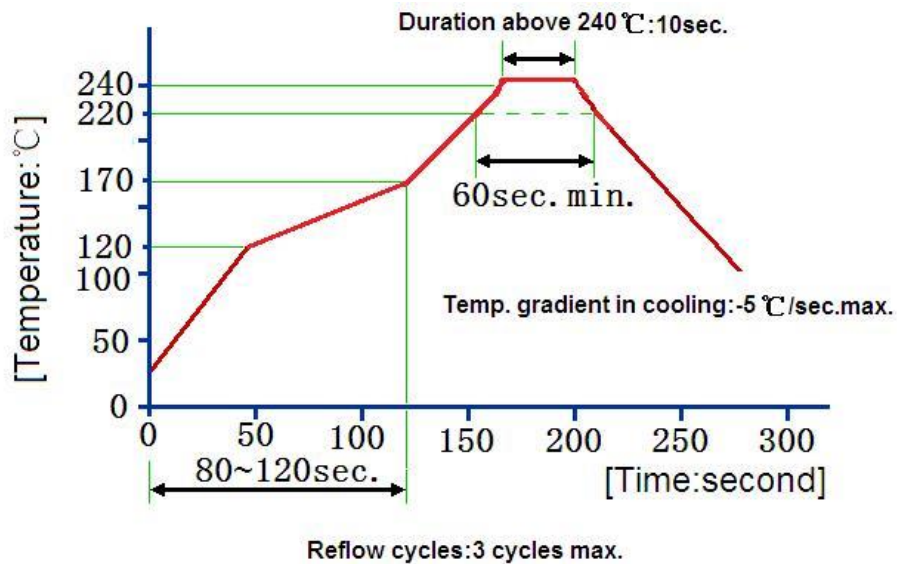
PARAMETER	SYMBOLS	CHARACTERISTICS			
		MIN.	TYPICAL	MAX.	UNIT
Center Frequency	FC	69.99	70	70.01	MHz
Insertion Loss	IL	-	12	4	dB
1 dB Bandwidth	BW <sub>1dB</sub>	0.8	0.85	-	MHz
3 dB Bandwidth	BW <sub>3dB</sub>	-	1.32	-	MHz
40 dB Bandwidth	BW <sub>40dB</sub>	-	3.28	3.5	MHz
Passband Ripple		-	0.5	1.0	dB
Group Delay Variation		-	80	160	nsec
Absolute Delay Time		-	1.25	-	µsec
Ultimate Attenuation		40	47	-	dB
Substrate Material & T.C.F		112-LiTaO <sub>3</sub> / -18			ppm/°C
Terminating Impedance		50			ohm

**MEASUREMENT CIRCUIT – FOR REFERENCE ONLY**

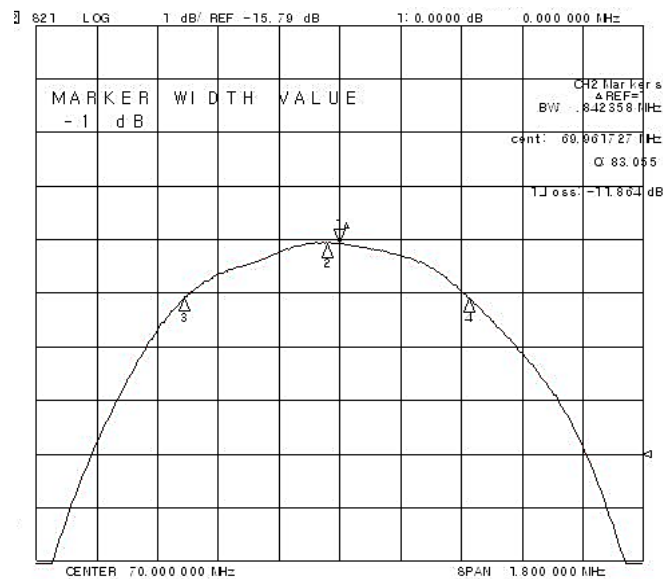
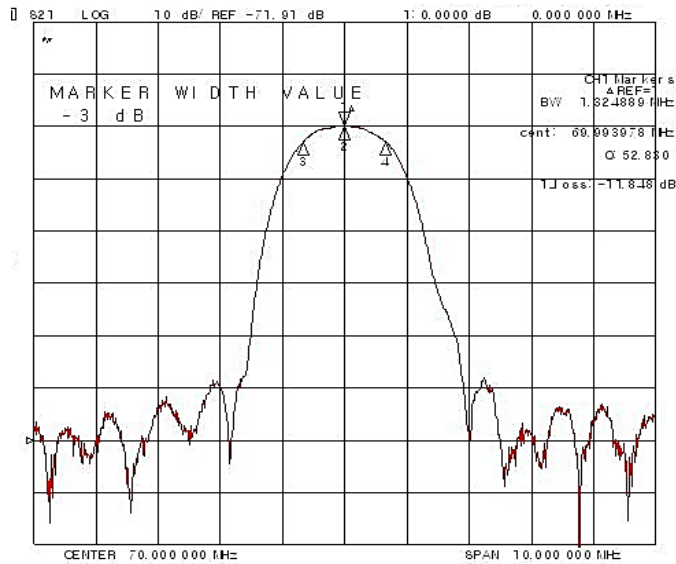


- L1=120nH, L2=68nH, C1=270pF, C2=16pF
- Source / Load Impedance = 50Ω
- Ambient Temperature = 25°C

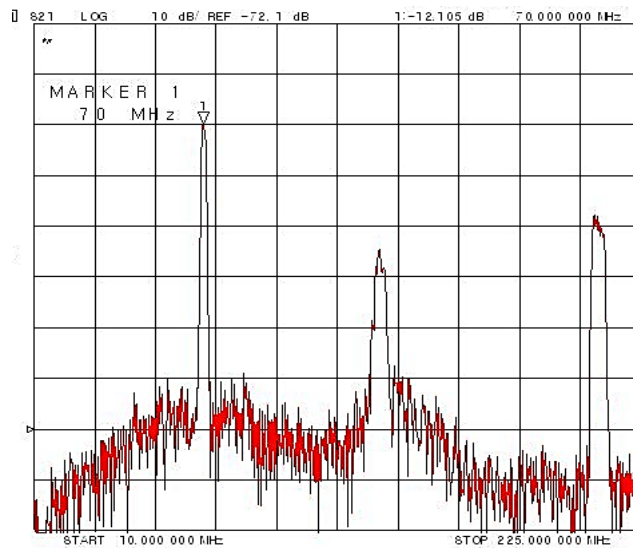
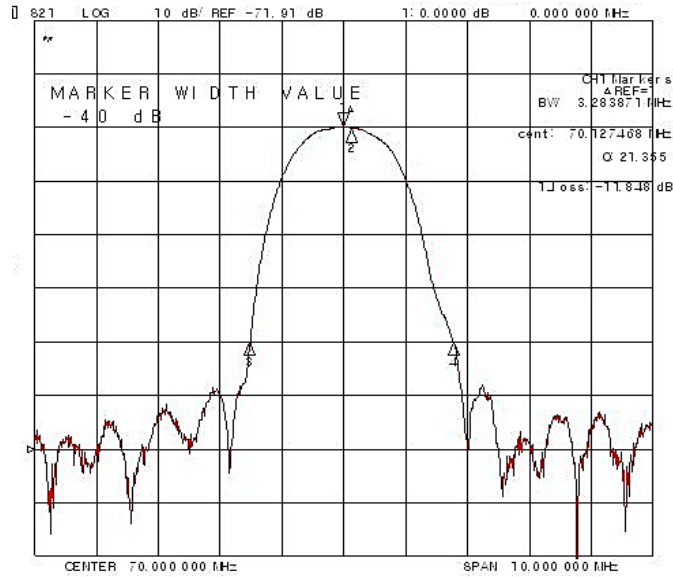
**RECOMMENDED SOLDERING PROFILE – FOR REFERENCE ONLY**



**FREQUENCY CHARACTERISTICS – FOR REFERENCE ONLY**

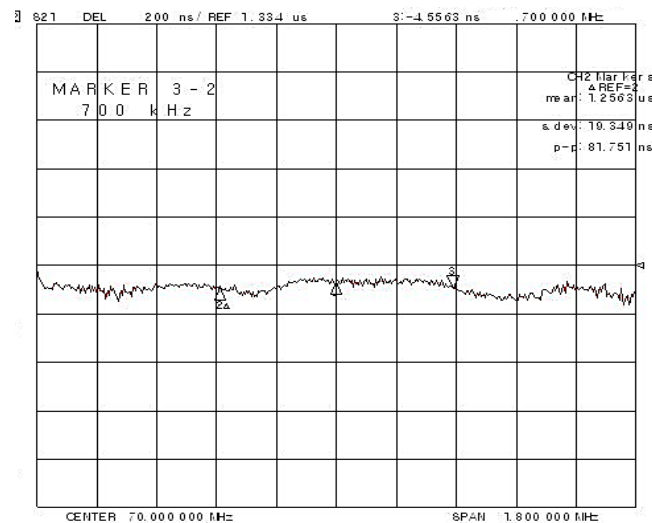
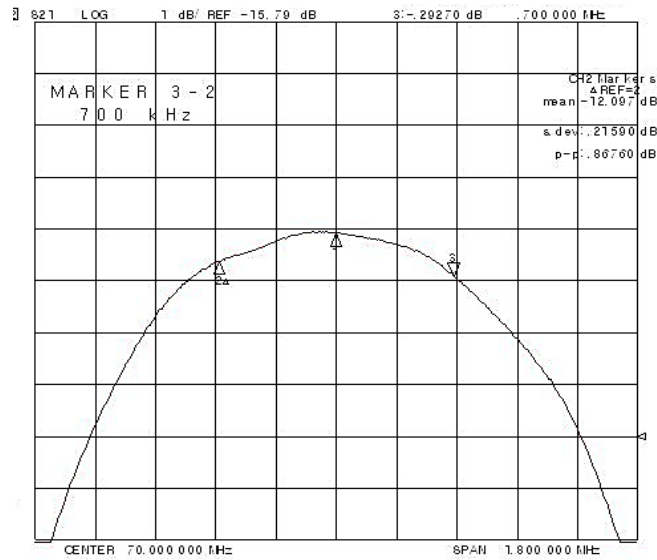


**FREQUENCY CHARACTERISTICS – FOR REFERENCE ONLY**





**FREQUENCY CHARACTERISTICS – FOR REFERENCE ONLY**



## RELIABILITY CHARACTERISTICS

TEST ITEMS	TEST METHOD AND CONDITIONS
High Temperature Storage	<ul style="list-style-type: none"> <li>Temperature: <math>85^{\circ}\text{C} \pm 2^{\circ}\text{C}</math>, Duration: 250h , Recovery time: <math>2\text{h} \pm 0.5\text{h}</math></li> <li>Temperature: <math>-40^{\circ}\text{C} \pm 3^{\circ}\text{C}</math>, Duration: 250h ,Recovery time: <math>2\text{h} \pm 0.5\text{h}</math></li> </ul>
Humidity Test	<ul style="list-style-type: none"> <li>Conditions: <math>60^{\circ}\text{C} \pm 2^{\circ}\text{C}</math> , 90~95% RH, Duration: 250h</li> </ul>
Thermal Shock	<ul style="list-style-type: none"> <li>Heat cycle conditions: <math>\text{TA} = -40^{\circ}\text{C} \pm 3^{\circ}\text{C}</math>, <math>\text{TB} = 85^{\circ}\text{C} \pm 2^{\circ}\text{C}</math>, <math>t_1 = t_2 = 30\text{min}</math>,</li> <li>Switch time: <math>\leq 3\text{min}</math>, Cycle time: 100 times,</li> <li>Recovery time: <math>2\text{h} \pm 0.5\text{h}</math>.</li> </ul>
Vibration Fatigue	<ul style="list-style-type: none"> <li>Frequency of vibration: 10~55Hz, Amplitude:1.5mm</li> <li>Directions: X,Y and Z, Duration: 2h</li> </ul>
Drop Test	<ul style="list-style-type: none"> <li>Cycle time: 10 times, Height: 1.0m</li> </ul>
Solderability	<ul style="list-style-type: none"> <li>Temperature: <math>245^{\circ}\text{C} \pm 5^{\circ}\text{C}</math>, Duration: 3.0s--5.0s, Depth: DIP--2/3 , SMD--1/5</li> </ul>
Resistance to Soldering Heat	<ul style="list-style-type: none"> <li>Thickness of PCB:1mm , Solder condition: <math>260^{\circ}\text{C} \pm 5^{\circ}\text{C}</math> , Duration: <math>10 \pm 1\text{s}</math></li> <li>Temperature of Soldering Iron: <math>350^{\circ}\text{C} \pm 10^{\circ}\text{C}</math> , Duration: 3~4s ,</li> <li>Recovery time : <math>2 \pm 0.5\text{h}</math></li> </ul>
Remarks	<ul style="list-style-type: none"> <li>As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to ESD protect in the test.</li> <li>Static voltage between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.</li> <li>Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.</li> <li>Only leads of component may be soldered. Please avoid soldering another part of component.</li> <li>There is a close relationship between the device's performance and matching network. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.</li> </ul>



## IMPORTANT NOTES AND DISCLAIMER

1. **ROHS COMPLIANCE:** The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU RoHS Directive (EU) 2015/863 EC (RoHS3). RoHS Test Report for this product can be obtained at Download Center.
2. **REACH COMPLIANCE:** REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, REACH Test Report for this product can be obtained at Download Center.
3. All Product parametric performance is indicated in the Electrical Characteristics for the listed herein test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
4. NextGen Component, Inc (*NextGen*) reserves the right to make changes to this document and its products and specifications at any time without notice. Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.
5. *NextGen* makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does *NextGen* assume any liability for application assistance or customer product design.
6. *NextGen* does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application. No license is granted by implication or otherwise under any intellectual property rights of NextGen.
7. *NextGen* products are not authorized for use as critical components in life support devices or systems without express written approval by *NextGen*.
8. *NextGen* requires that customers first obtain an RMA (Returned Merchandise Authorization) number prior to returning any products. Returns must be made within 30 days of the date of invoice, be in the original packaging, unused and like-new condition. At the time of quoting or purchasing, a product may say that it is Non-Cancelable/ Non-Returnable (NCNR). These products are not returnable and not refundable.